

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A composition, comprising:

an organic conductive material and at least one species of solvent, ~~wherein the changing rate of the viscosity is within a range of ±5% when 30 days have passed after the preparation~~ the solvent containing a glycol medium and an acetylenic alcohol surfactant, and the content of the acetylenic alcohol surfactant in the solvent ranging from 0.01 to 0.1 percent by weight.

2. (Canceled)

3. (Currently Amended) The composition according to Claim 21, the content of the glycol medium in the solvent ranging from 40 to 55 percent by weight.

4. (Currently Amended) The composition according to Claim 21, the glycol medium including diethylene glycol and a mixture containing the same.

5. (Currently Amended) The composition according to Claim 21, the glycol medium including monoethylene glycol and a mixture containing the same.

6. (Currently Amended) The composition according to Claim 21, the glycol medium including triethylene glycol and a mixture containing the same.

7. (Previously Presented) The composition according to Claim 1, the organic conductive material including polythiophene derivatives.

8. (Previously Presented) The composition according to Claim 1, the organic conductive material including a mixture of polydioxathiophene and polystyrene sulfonic acid.

9. (Withdrawn) The composition according to Claim 1, the organic conductive material including a mixture of polyaniline and polystyrene sulfonic acid.

- 10-11. (Canceled)

12. (Currently Amended) The composition according to Claim 101, the acetylenic alcohol surfactant having a boiling point that is less than or equal to that of the medium as well as the surfactant contained in the solvent.

13. (Currently Amended) The composition according to Claim 101, the acetylenic alcohol surfactant includes 3,5-dimethyl-1-octyne-3-ol.

14. (Previously Presented) The composition according to Claim 1, the composition being subjected to degassing treatment.

15. (Previously Presented) The composition according to Claim 14, the degassing treatment being performed at a vacuum pressure that is less than or equal to the saturation vapor pressure of water.

16. (Previously Presented) The composition according to Claim 14, before the degassing treatment, the composition containing an amount of the medium vaporized in the degassing treatment in advance.

17. (Withdrawn) An organic semiconductive layer, comprising:
a composition according to Claim 1.

18. (Withdrawn) A method to manufacture organic conductive layers, comprising:
applying a composition to different portions by an inkjet process, the composition being set forth in Claim 1.

19. (Withdrawn) The organic conductive layer-manufacturing method according to Claim 18, further comprising:

removing a solvent after the application step.

20. (Withdrawn) The organic conductive layer-manufacturing method according to Claim 19, the removing being performed in a vacuum atmosphere.

21. (Withdrawn) The organic conductive layer-manufacturing method according to Claim 20, the removing being performed at a pressure of 1.333×10^{-3} Pa or less and a temperature substantially equal to room temperature.

22. (Withdrawn) The organic conductive layer-manufacturing method according to Claim 19, further comprising:

performing thermal treatment at 100°C or more after the removing.

23. (Withdrawn) The organic conductive layer-manufacturing method according to Claim 22, a heat source used in the thermal treatment including infrared rays.

24. (Withdrawn) An organic EL element, comprising:

a hole injection/transport layer including the organic conductive layer according to Claim 17.

25. (Withdrawn) A method to manufacture organic EL elements, comprising: forming hole injection/transport layers each including the organic conductive layer according to Claim 17 by an inkjet process.

26. (Withdrawn) An electronic device, comprising:

at least the organic EL element according to Claim 24 and a circuit to drive the organic EL element.

27. (Withdrawn) An electronic apparatus, comprising:

the electronic device according to Claim 26.

28. (Withdrawn) An organic semiconductor element, comprising:

a source, a drain, a gate or wiring lines, which are conductive portions included in an integrated circuit, each including the organic conductive layer according to Claim 17.

29. (Withdrawn) A method for manufacturing organic semiconductor elements, comprising:

forming a drain, a gate or wiring lines, which are conductive portions included in an integrated circuit, by an inkjet process using the organic conductive layer according to Claim 17.